

## Overview

The purpose of this notification is to communicate the qualification of a new epoxy molding compound (EMC) for PROMs PD(G)8 package. Xilinx’s Assembly Supplier will discontinue use of all Dongjin EMCs by end of 2013. This notification applies to all XC Commercial (C) and Industrial (I) grade PROMs products and does not impact Automotive (XA) or Hi-Rel (XQ) products.

## Description

Xilinx’s Assembly Supplier is standardizing their epoxy molding compound to Panasonic (Cookson) CK5000A from Dongjin DMC2000 series for all PD(G) 8 packages.

## Products Affected

This change affects all standard part numbers and specification control document (SCD) versions of the XC Commercial (C) and Industrial (I) grade standard part numbers listed in [Table 1](#).

Table 1: Affected PROMs device families

Device-Package-Grade	Device-Package-Grade	Device-Package-Grade
XC17S100A-PD8-C	XC17S15A-PD8-I	XC17S30A-PD8-C
XC17S100A-PD8-I	XC17S200A-PD8-C	XC17S30A-PD8-I
XC17S150A-PD8-C	XC17S200A-PD8-I	XC17S50A-PD8-C
XC17S150A-PD8-I	XC17S200A-PDG8-C	XC17S50A-PD8-I
XC17S15A-PD8-C	XC17S200A-PDG8-I	XC17S50A-PDG8-C

## Key Dates and Traceability

Xilinx will begin to cross ship both current and new epoxy molding compound by January 1<sup>st</sup>, 2014 (date code: 1401). The Date Code can be found on the package top mark (see [Figure 1](#)).



Figure 1: Top Mark

## Qualification Data

The Supplier has already qualified the Panasonic (Cookson) CK5000A EMC with PD(G) packages and has been in production since 2012. Xilinx will perform additional qualification using Xilinx device/packages listed in [Table 2](#). Xilinx qualification data will be available per the schedule in [Table 3](#).

Table 2: Qualification Plan

Device	Package	Reliability Test	SS
XC17S200A	PDG8	HTS 1000 hrs.	25 x 3 lots
		TCB 1000 cycles	25 x 3 lots
		THB 1000 hrs.	25 x 3 lots

Table 3: Qualification Schedule

Package Type	New epoxy molding compound	Conditional Qualification	Estimated Production Release Schedule
Wire Bond PD(G) 8 Package	Panasonic (Cookson) CK5000A	Completed	January 1 <sup>st</sup> , 2014

## Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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## Additional Documentation

Qualification Report (RPT137):

<https://secure.xilinx.com/webreg/clickthrough.do?cid=345449>.

## Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
09/30/13	1.0	Initial release.
11/07/13	1.0.1	Replace the Qualification Report URL link with a click through CID code.

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